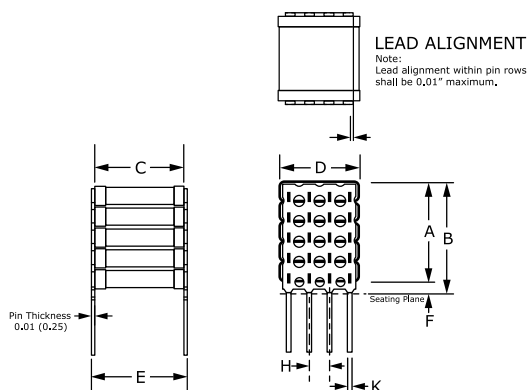


KPS-MCC Indust COG HT200C, Ceramic, 0.27 uF, 10%, 1000 VDC, COG



Dimensions

| | |
|---|--------------------|
| D | 10.16mm +/-0.635mm |
| L | 6.35mm MIN |
| H | 2.54mm NOM |
| F | 1.397mm +/-0.25mm |
| A | 13.46mm MAX |
| B | 15.238mm MAX |
| C | 10.16mm +/-0.635mm |
| E | 11.18mm MAX |
| K | 0.5mm NOM |

Packaging Specifications

| | |
|---------------------|-------------|
| Packaging: | Waffle, Box |
| Packaging Quantity: | 16 |

General Information

| | |
|--------------|---|
| Series: | KPS-MCC Indust COG HT200C |
| Style: | Leaded Stacked Chip |
| Description: | Low ESR, Stacked Ceramic Chips |
| Features: | 200C, Low ESR, High Thermal Stability, Bulk Capacitance |
| RoHS: | With Exemptions |
| REACH: | SVHC (Pb – CAS 7439-92-1) |
| Termination: | Silver |
| Lead: | Straight Leads |
| Notes: | Number of chips in this stack: 5 |

Specifications

| | |
|----------------------------------|---------------------|
| Capacitance: | 0.27 uF |
| Capacitance Tolerance: | 10% |
| Voltage DC: | 1000 VDC |
| Dielectric Withstanding Voltage: | 1200 VDC |
| Temperature Range: | -55/+200°C |
| Temperature Coefficient: | COG |
| Dissipation Factor: | 0.10% 1kHz 25C |
| Aging Rate: | 0% Loss/Decade Hour |
| Insulation Resistance: | 3.7 GOhms |